

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: (Divisional of U.S. Serial No. 09/322,416 which is
a Continuation of U.S. Serial No. 09/187,617)
Filed: July 3, 2001
Applicant: Austin et al.
Title: **METHOD FOR VACUUM ENCAPSULATION OF
SEMICONDUCTOR CHIP PACKAGES**
Our Ref. No.: NOR-865B

Cincinnati, OH

July 3, 2001

Assistant Commissioner for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Prior to examination of the above-identified application, please
amend the application as follows:

In the Specification:

On page 1, line 1, please insert the following: --The present
application is a divisional of co-pending U.S. Serial No. 09/322,416, filed
May 28, 1999, which is a continuation of U.S. Serial No. 09/187,617, filed
November 6, 1998, the disclosures of which are hereby incorporated herein
by reference in their entirety.--

In the Claims:


Please cancel claims 12-21 without prejudice or disclaimer.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned **"Version with markings to show changes made"**.

If any additional fees are necessary to complete this communication, the Commissioner is hereby authorized to charge same to Deposit Account 23-3000.

Respectfully submitted,

WOOD, HERRON & EVANS, L.L.P.

By 
David H. Brinkman
Reg. No. 40,532

2700 Carew Tower
441 Vine Street
Cincinnati, OH 45202
(513) 241-2324 - Office
(513) 421-7269 - Facsimile

VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the Specification:

On page 1, line 1, please insert the following: --The present application is a divisional of co-pending U.S. Serial No. 09/322,416, filed May 28, 1999, which is a continuation of U.S. Serial No. 09/187,617, filed November 6, 1998, the disclosures of which are hereby incorporated herein by reference in their entirety.--

In the Claims:

Claims 12-21 have been canceled.